# 3.3V ECL 2:8 Differential **Fanout Buffer**

The MC100LVE310 is a low voltage, low skew 2:8 differential ECL fanout buffer designed with clock distribution in mind. The device features fully differential clock paths to minimize both device and system skew. The LVE310 offers two selectable clock inputs to allow for redundant or test clocks to be incorporated into the system clock

To ensure that the tight skew specification is met it is necessary that both sides of the differential output are terminated into 50  $\Omega$  even if only one side is being used. In most applications all eight differential pairs will be used and therefore terminated. In the case where fewer than eight pairs are used it is necessary to terminate at least the output pairs adjacent to the output pair being used in order to maintain minimum skew. Failure to follow this guideline will result in small degradations of propagation delay (on the order of 10–20 ps) of the outputs being used, while not catastrophic to most designs this will result in an increase in skew. Note that the package corners isolate outputs from one another such that the guideline expressed above holds only for outputs on the same side of the package.

The MC100LVE310, as with most ECL devices, can be operated from a positive V<sub>CC</sub> supply in LVPECL mode. This allows the LVE310 to be used for high performance clock distribution in +3.3 V systems. Designers can take advantage of the LVE310's performance to distribute low skew clocks across the backplane or the board. In a PECL environment series or Thevenin line terminations are typically used as they require no additional power supplies, if parallel termination is desired a terminating voltage of V<sub>CC</sub>-2.0 V will need to be provided. For more information on using PECL, designers should refer to Application Note AN1406/D.

The VBB pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to VBB as a switching reference voltage. V<sub>BB</sub> may also rebias AC coupled inputs. When used, decouple V<sub>BB</sub> and  $V_{\mbox{CC}}$  via a 0.01  $\mu \mbox{F}$  capacitor and limit current sourcing or sinking to 0.5 mA. When not used, VBB should be left open.

- 200 ps Part-to-Part Skew
- 50 ps Output-to-Output Skew
- The 100 Series Contains Temperature Compensation
- ESD Protection: >2 KV HBM, >200 V MM
- PECL Mode Operating Range: V<sub>CC</sub>= 3.0 V to 3.8 V with V<sub>EE</sub>= 0 V
- NECL Mode Operating Range: VCC= 0 V with VEE= -3.0 V to -3.8 V
- Internal Input Pulldown Resistors
- Q Output will Default LOW with All Inputs Open or at VEE
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity Level 1 For Additional Information, see Application Note AND8003/D
- Flammability Rating: UL-94 code V-0 @ 1/8", Oxygen Index 28 to 34
- Transistor Count = 212 devices



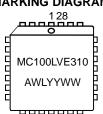
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#### **MARKING DIAGRAM**







= Assembly Location

WL = Wafer Lot

YY = Year

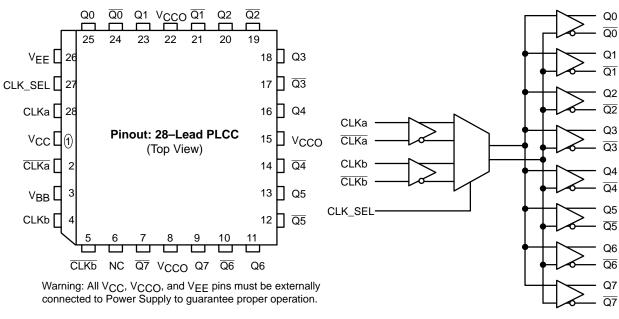
WW = Work Week

## ORDERING INFORMATION

Device	Package	Shipping
MC100LVE310FN	PLCC-28	37 Units/Rail
MC100LVE310FNR2	PLCC-28	500 Units/Reel

#### LOGIC DIAGRAM AND PINOUT ASSIGNMENT

#### LOGIC SYMBOL



#### **PIN DESCRIPTION**

PIN	FUNCTION
CLKa, CLKa; ,CLKb CLKb Q0:7, Q0:7 CLK_SEL VBB VCC, VCCO VEE NC	ECL Differential Input Clocks ECL Differential Outputs ECL Input Clock Select Reference Voltage Output Positive Supply Negative Supply No Connect

CLK_SEL	Input Clock
Ι	CLKa Selected CLKb Selected

V<sub>BB</sub> -

## MAXIMUM RATINGS (Note 1)

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
VCC	PECL Mode Power Supply	V <sub>EE</sub> = 0 V		8 to 0	V
VEE	NECL Mode Power Supply	VCC = 0 V		-8 to 0	V
VI	PECL Mode Input Voltage	VEE = 0 V	$V_I \leq V_{CC}$	6 to 0	V
	NECL Mode Input Voltage	VCC = 0 V	$V_I \ge V_{EE}$	–6 to 0	V
l <sub>out</sub>	Output Current	Continuous Surge		50 100	mA mA
I <sub>BB</sub>	V <sub>BB</sub> Sink/Source			± 0.5	mA
TA	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
θJA	Thermal Resistance (Junction to Ambient)	0 LFPM 500 LFPM	28 PLCC 28 PLCC	63.5 43.5	°C/W
θJC	Thermal Resistance (Junction to Case)	std bd	28 PLCC	22 to 26 ± 5%	°C/W
T <sub>sol</sub>	Wave Solder	<2 to 3 sec @ 248°C		265	°C

<sup>1.</sup> Maximum Ratings are those values beyond which device damage may occur.

#### LVPECL DC CHARACTERISTICS V<sub>CC</sub>= 3.3 V; V<sub>EE</sub>= 0.0 V (Note 1)

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
IEE	Power Supply Current		55	60		55	60		65	70	mA
VOH	Output HIGH Voltage (Note 2)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V <sub>OL</sub>	Output LOW Voltage (Note 2)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
V <sub>IH</sub>	Input HIGH Voltage (Single Ended)	2135		2420	2135		2420	2135		2420	mV
V <sub>IL</sub>	Input LOW Voltage (Single Ended)	1490		1825	1490		1825	1490		1825	mV
V <sub>BB</sub>	Output Voltage Reference	1.92		2.04	1.92		2.04	1.92		2.04	V
VIHCMR	Input HIGH Voltage Common Mode Range (Differential) (Note 3)	1.8		2.9	1.8		2.9	1.8		2.9	V
liH	Input HIGH Current			150			150			150	μΑ
IIL	Input LOW Current	0.5			0.5			0.5			μΑ

NOTE: Devices are designed to meet the DC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained.

- Input and output parameters vary 1:1 with V<sub>CC</sub>. V<sub>EE</sub> can vary ±0.3 V.
   Outputs are terminated through a 50 ohm resistor to V<sub>CC</sub>-2 volts.
   V<sub>IHCMR</sub> min varies 1:1 with V<sub>EE</sub>, max varies 1:1 with V<sub>CC</sub>. V<sub>IHCMR</sub> is defined as the range within which the V<sub>IH</sub> level may vary, with the device still meeting the propagation delay specification. The V<sub>IL</sub> level must be such that the peak to peak voltage is less than 1.0 V and greater than or equal to Vpp(min).

#### LVNECL DC CHARACTERISTICS V<sub>CC</sub>= 0.0 V; V<sub>EE</sub>= -3.3 V (Note 1)

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
IEE	Power Supply Current		55	60		55	60		65	70	mA
Vон	Output HIGH Voltage (Note 2)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
VOL	Output LOW Voltage (Note 2)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
VIH	Input HIGH Voltage (Single Ended)	-1165		-880	-1165		-880	-1165		-880	mV
V <sub>IL</sub>	Input LOW Voltage (Single Ended)	-1810		-1475	-1810		-1475	-1810		-1475	mV
V <sub>BB</sub>	Output Voltage Reference	-1.38		-1.26	-1.38		-1.26	-1.38		-1.26	V
VIHCMR	Input HIGH Voltage Common Mode Range (Differential) (Note 3)	-1.5		-0.4	-1.5		-0.4	-1.5		-0.4	V
liH	Input HIGH Current			150			150			150	μΑ
I <sub>I</sub> L	Input LOW Current	0.5			0.5			0.5			μА

NOTE: Devices are designed to meet the DC specifications shown in the above table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained.

- Input and output parameters vary 1:1 with V<sub>CC</sub>. V<sub>EE</sub> can vary ±0.3 V.
   Outputs are terminated through a 50 ohm resistor to V<sub>CC</sub>-2 volts.
   V<sub>IHCMR</sub> min varies 1:1 with V<sub>EE</sub>, max varies 1:1 with V<sub>CC</sub>. V<sub>IHCMR</sub> is defined as the range within which the V<sub>IH</sub> level may vary, with the device still meeting the propagation delay specification. The V<sub>IL</sub> level must be such that the peak to peak voltage is less than 1.0 V and greater than or equal to Vpp(min).

AC CHARACTERISTICS  $V_{CC}$ = 3.3 V;  $V_{EE}$ = 0.0 V or  $V_{CC}$ = 0.0 V;  $V_{EE}$ = -3.3 V (Note 1.)

			–40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f <sub>max</sub>	Maximum Toggle Frequency		TBD			TBD			TBD		GHz
<sup>t</sup> PLH <sup>t</sup> PHL	Propagation Delay to Output IN (differential) (Note 2.) IN (single–ended) (Note 3.)	525 500		725 750	550 550		750 800	575 600		775 850	ps
tskew	Within–Device Skew (Note 4.) Part–to–Part Skew (Differential)			75 250			50 200			50 200	ps
<sup>t</sup> JITTER	Cycle-to-Cycle Jitter		TBD			TBD			TBD		ps
V <sub>PP</sub>	Input Swing (Note 5.)	500		1000	500		1000	500		1000	mV
t <sub>r</sub> /t <sub>f</sub>	Output Rise/Fall Time (20%-80%)	200		600	200		600	200		600	ps

- 1. VEE can vary ±0.3 V.
- 2. The differential propagation delay is defined as the delay from the crossing points of the differential input signals to the crossing point of the differential output signals.
- 3. The single-ended propagation delay is defined as the delay from the 50% point of the input signal to the 50% point of the output signal.
- 4. The within-device skew is defined as the worst case difference between any two similar delay paths within a single device.
- 5. Vpp(min) is defined as the minimum input differential voltage which will cause no increase in the propagation delay. The Vpp(min) is AC limited for the LVE310 as a differential input as low as 50 mV will still produce full ECL levels at the output.

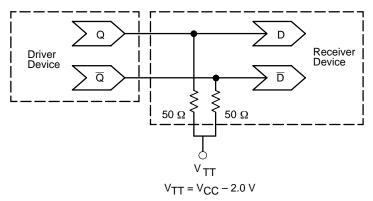


Figure 1. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020 – Termination of ECL Logic Devices.)

#### **Resource Reference of Application Notes**

AN1404 – ECLinPS Circuit Performance at Non–Standard VIH Levels

AN1405 – ECL Clock Distribution Techniques

AN1406 - Designing with PECL (ECL at +5.0 V)

AN1503 - ECLinPS I/O SPICE Modeling Kit

**AN1504** – Metastability and the ECLinPS Family

AN1560 – Low Voltage ECLinPS SPICE Modeling Kit

AN1568 – Interfacing Between LVDS and ECL

AN1596 – ECLinPS Lite Translator ELT Family SPICE I/O Model Kit

AN1650 – Using Wire–OR Ties in ECLinPS Designs

AN1672 - The ECL Translator Guide

AND8001 - Odd Number Counters Design

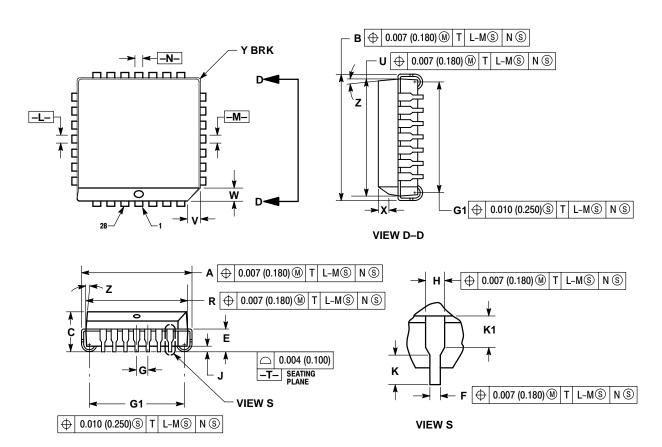
AND8002 – Marking and Date Codes

AND8020 - Termination of ECL Logic Devices

#### PACKAGE DIMENSIONS

#### PLCC-28 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 776-02 **ISSUE E** 



### NOTES:

- NOTES:

  1. DATUMS L. –, –M. –, AND N. DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

  2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM –T. –, SEATING PLANE.

  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

  4. DIMENSIONING AND TOLERANCING PER ANS 1/14 SM 1982.
- ANSI Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH.
- 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE
- PLASTIC BODY.
  7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.485	0.495	12.32	12.57
В	0.485	0.495	12.32	12.57
С	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.450	0.456	11.43	11.58
υ	0.450	0.456	11.43	11.58
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Х	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2 °	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040		1.02	

# **Notes**



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